

General Description

The MY8808BBNE3 is the highest performance trench N-CH MOSFETS with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the small power switching and load switch applications.

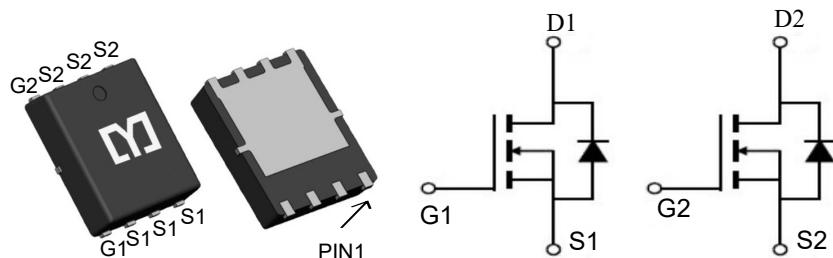


Features

V_{DSS}	20	V
I_D	7	A
$R_{DS(ON)}(\text{at } V_{GS}=4.5V)$	<14.5	$m\Omega$
$R_{DS(ON)}(\text{at } V_{GS}=2.5V)$	<17	$m\Omega$

Application

- Battery protection
- Load switch
- Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY8808BBNE3	PDFN3*3-8	NULL	5000

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	7	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	5.8	A
I_{DM}	Pulsed Drain Current ²	70	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation ¹	1.56	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	80	$^\circ C/W$

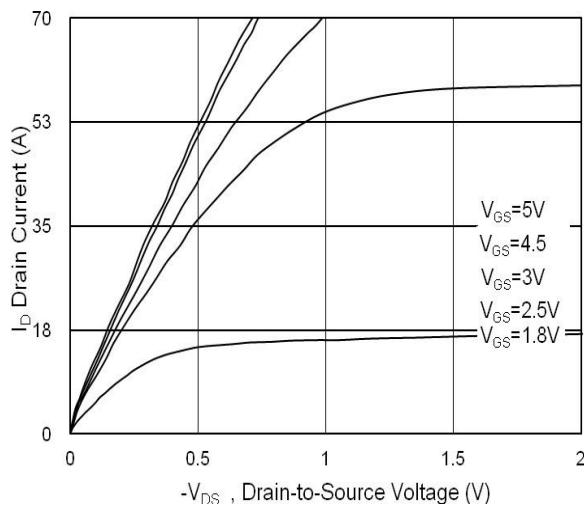
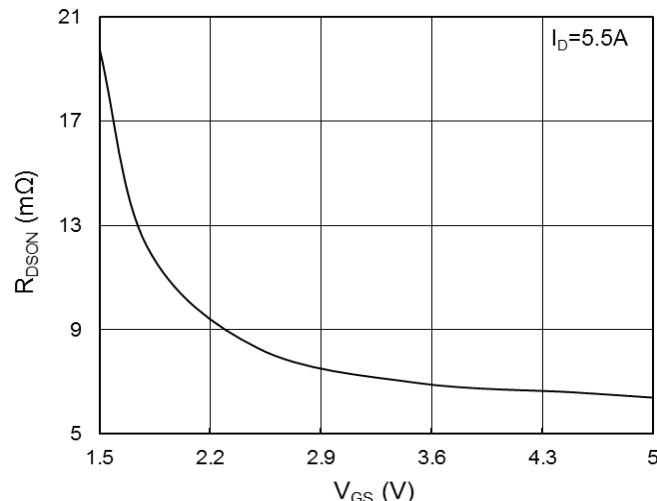
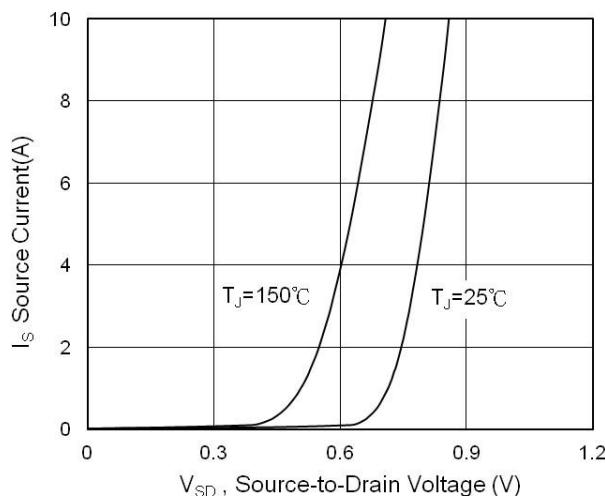
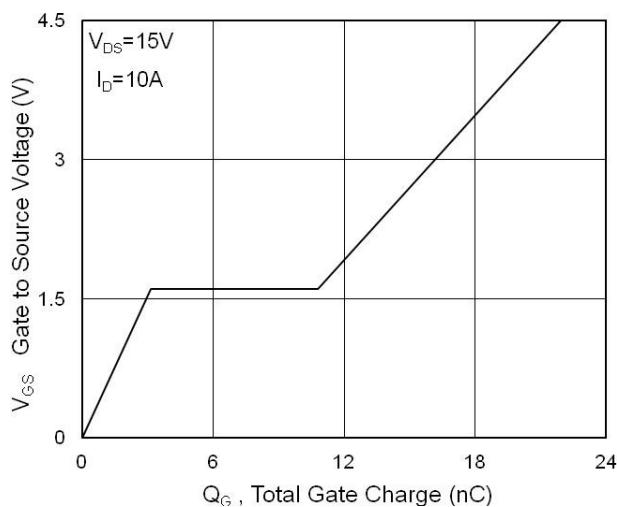
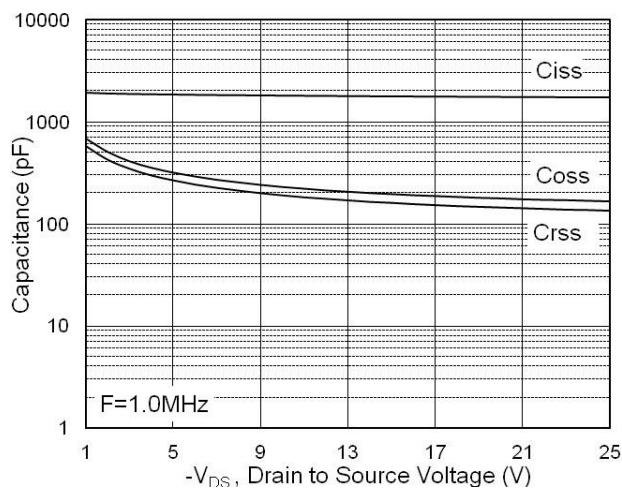
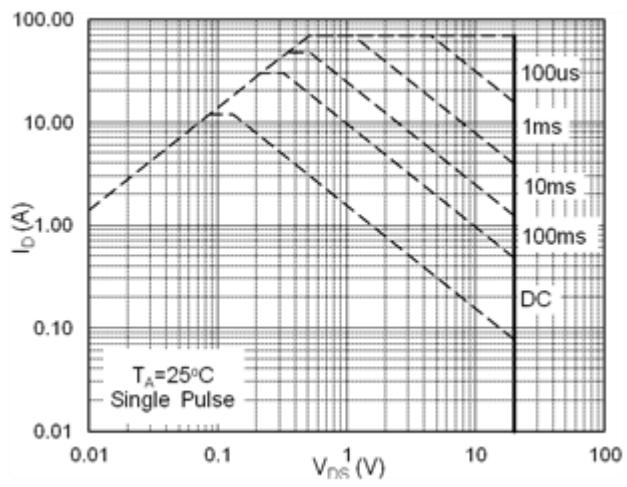
Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	20	---	---	V
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=5.5\text{A}$	14.5	16	19.5	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=3.7\text{V}$, $\text{I}_D=5.5\text{A}$	15.0	17.5	20.5	
		$\text{V}_{\text{GS}}=2.5\text{V}$, $\text{I}_D=5.5\text{A}$	17	18.2	22.2	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	0.5	---	1.5	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=18\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=18\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 12\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 10	μA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$, $\text{I}_D=5.5\text{A}$	---	38	---	S
Q_g	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=16\text{V}$, $\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=10\text{A}$	---	23	---	nC
Q_{gs}	Gate-Source Charge		---	3.5	---	
Q_{gd}	Gate-Drain Charge		---	8.4	---	
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=16\text{V}$, $\text{V}_{\text{GS}}=4.5\text{V}$, $\text{R}_G=6\text{ }\Omega$, $\text{I}_D=5.5\text{A}$	---	10.2	---	ns
T_r	Rise Time		---	41	---	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	67	---	
T_f	Fall Time		---	31	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=10\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1767	---	pF
C_{oss}	Output Capacitance		---	184	---	
C_{rss}	Reverse Transfer Capacitance		---	155	---	
I_{s}	Continuous Source Current ¹	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	11	A
I_{SM}	Pulsed Source Current ²		---	---	70	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_{\text{s}}=11\text{A}$, $\text{T}_J=25^\circ\text{C}$	---	---	1.2	V

Note :

1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, $t \leq 10\text{s}$.2.The data tested by pulsed , pulse width $\leq 10\text{us}$, duty cycle $\leq 1\%$

Typical Characteristics

**Fig.1 Typical Output Characteristics****Fig.2 OResistance vs Gate Source****Fig.3 Forward Characteristics of Reverse****Fig.4 Gate-Charge Characteristics****Fig.5 VGS(th)vs. TJ****Fig.6 Normalized RDSONvs. TJ**

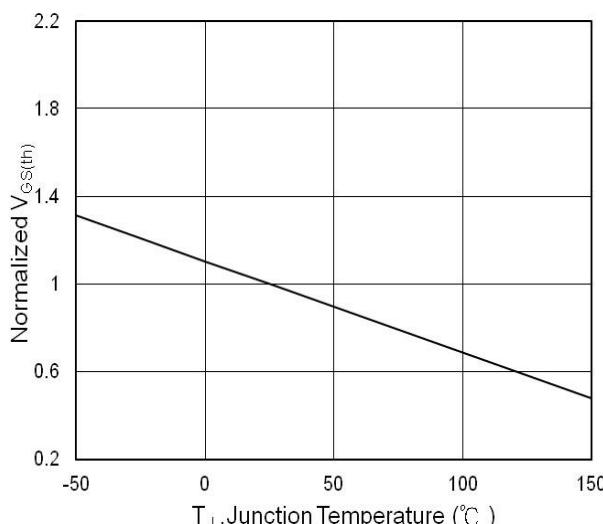


Fig.8 Safe Operating Area

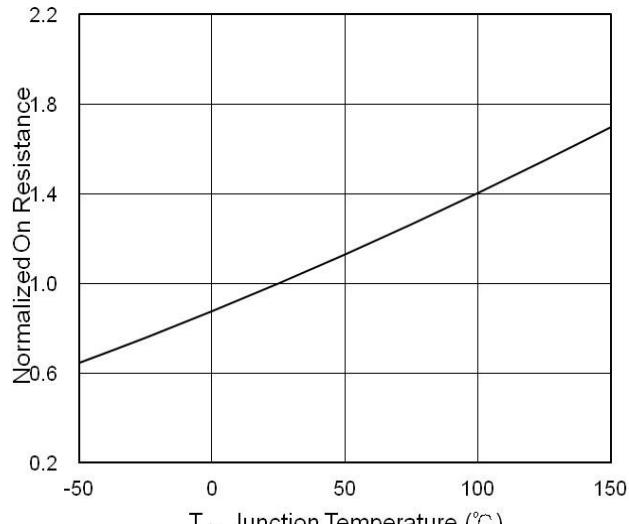


Fig.7 Capacitance

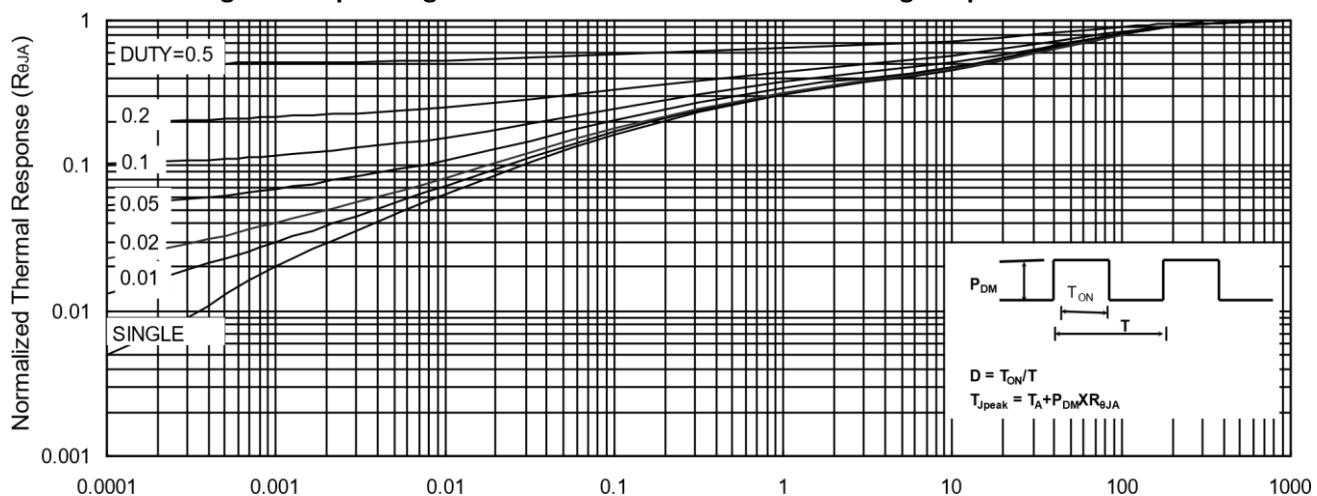


Fig.9 Normalized Maximum Transient Thermal Impedance

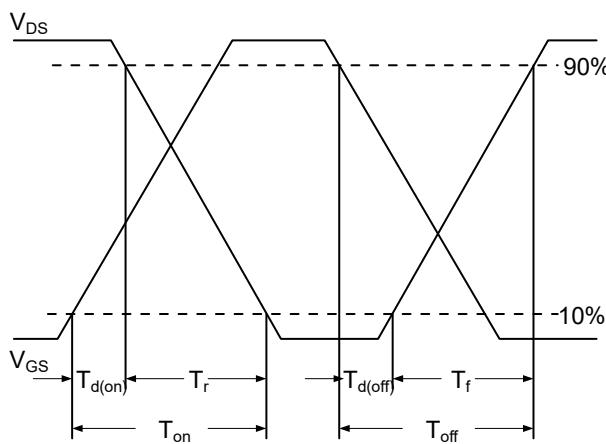


Fig.10 Switching Time Waveform

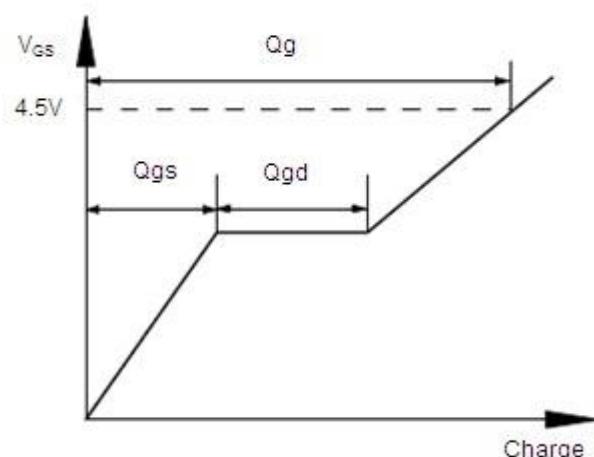
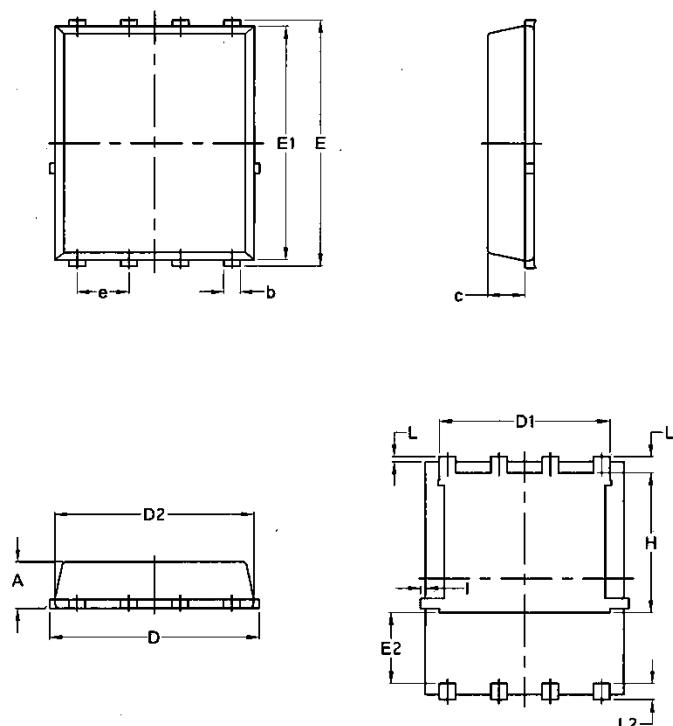


Fig.11 Gate Charge Waveform

Package Mechanical Data-DFN5*6-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070